1 is replaced by the volume of material **19** of FIG. 23. The volume of material **19** of FIG. 23 may include any material (e.g., a nonsolderable and nonconductive material such as a polyimide or a photosensitive resin) that could be included in the coat of material **18** of FIG. 1, or additionally epoxy adhesive or silicone adhesive. The first substrate **12** (e.g., chip, module), first conductive bodies **14** (e.g., solder bump such as C4 solder ball), and pads **16** in FIG. 23 are the same as in FIG. 1. All processes, materials, etc. described *supra* for FIG. 1 apply to FIG. 23 except for differences attributable to the geometrical difference between the volume of material **19** of FIG. 23 and the coat of material **18** of FIG. 1. The volume of material **19** is said to volumetrically surround the conductive bodies **44**. As seen in FIGS. 23-28, the volume of material **19** is continuously distributed between the two first conductive bodies **14** shown in FIGS. 23-28, and the volume of material **19** fills a space between the two first conductive bodies **14** shown in FIGS. 23-28.

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In The Claims

Currently pending claims 1-18 and 40-41 are as follows based on the amendment herein, wherein claims 1 and 18 have been amended, and wherein claims 40 and 41 are new:

1. (AMENDED) An electrical structure, comprising:

a first substrate;

a first conductive body mechanically and electrically coupled to the first substrate;

A2 a third conductive body mechanically and electrically coupled to the first substrate;

a nonsolderable and nonconductive material, wherein the nonsolderable and nonconductive material volumetrically surrounds and contacts a first portion of a surface of the